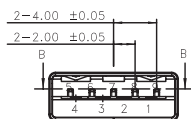
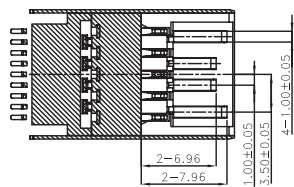
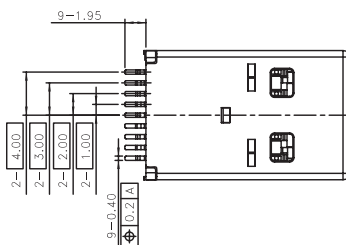
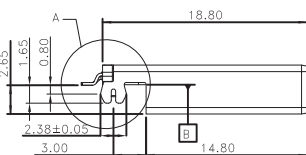
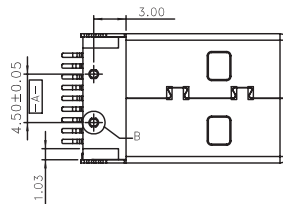


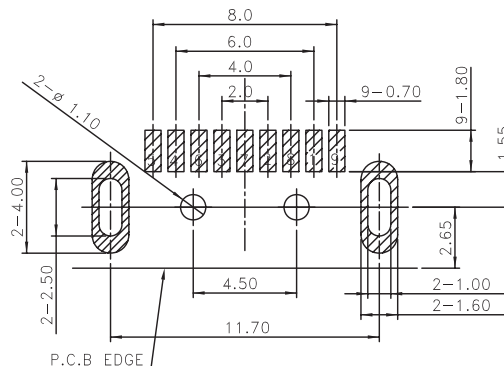
DETAIL A



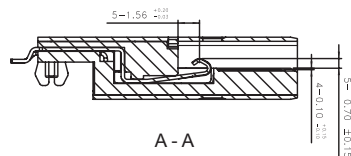
DETAIL B



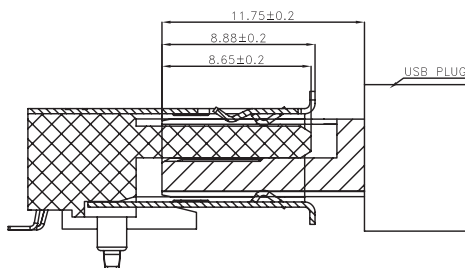
B - B



PCB LAYOUT - COMPONENT VIEW



A - A



TECHNICAL CHARACTERISTICS

MATERIAL
 INSULATOR: LCP
 FLAMMABILITY RATING: UL94-V0
 COLOR: BLUE
 CONTACT MATERIAL: PHOSPHORE BRONZE
 CONTACT TYPE: STAMPED
 CONTACT PLATING: UNDERPLATE 1.27 to 2.54 µm Ni
 CONTACT AREA 0.76 µm Gold
 SOLDER TAIL AREA 2.54 to 5.08 µm Matt Tin
 SHIELDING: STEEL BRIGHT TIN PLATED
 QUALITY CLASS: 5000 MATING CYCLES

ENVIRONMENTAL
 OPERATING TEMPERATURE: -20°C up to +85°C
 COMPLIANCE: LEAD FREE & RoHS

ELECTRICAL
 CURRENT RATING:
 - PIN 1 & PIN 4 (Vbus & corresponding ground PIN) 1.8A MAX
 - OTHER PINS 0.25 A MAX
 WORKING VOLTAGE: 30 VAC
 DIELECTRIC WITHSTANDING VOLTAGE: 100 VAC/MIN
 INSULATION RESISTANCE: > 100 MΩ
 CONTACT RESISTANCE:
 - PIN 1 & PIN 4: 30mΩ MAX
 - OTHER PINS: 50mΩ MAX

STANDARD
 CERTIFIED: E323964

MECHANICAL
 INSERTION FORCE: 35.0N MAX
 EXTRACTION FORCE: 10.0N MIN

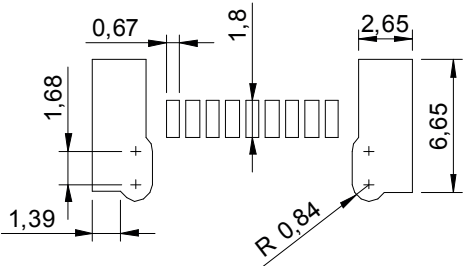
SOLDERING
 JEDEC LEAD FREE REFLOW SOLDERING

PACKAGING
 TRAY

* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.

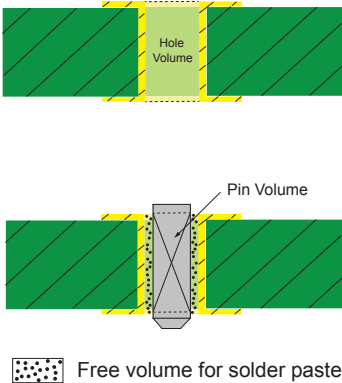
RoHS Compliant				* NOTE: THE RECOMMENDED PCB LAYOUT IS FOR AN OPTIMIZED RETENTION FORCE OF CONNECTOR ON PCB BUT IT IMPLIES INSERTION FORCE THAT A LOT OF PICK AND PLACE MACHINES ARE NOT ABLE TO HANDLE. THEREFORE IT MIGHT BE NECESSARY TO DRILL BIGGER HOLES FOR THE CLIPS. PLEASE CHECK THIS CAREFULLY.			
				PROJECTION: 	GENERAL TOLERANCE .X = $\pm$ 0.2 .XX = $\pm$ 0.15		
				APPROVAL: NPr	UNIT: MM	DESCRIPTION: WR COM - USB 3.0 SMT PLUG WITH CLIP TYPE A	SIZE A4
					SCALE:		
H	10-JAN-15	TOLERANCES	QP		SHEET: 1/4	WERI PART NO: 692 112 030 100	
REV	DATE	FILE	BY		DRAW: AS		

Stencil information for Through Hole Reflow soldering



STENCIL LAYOUT * - COMPONENT VIEW

PCB cross section



Theoretical Formula for Through Hole pins
Volume of the stencil aperture = (Hole volume - Pin volume) x 2
or
Volume of solder paste = (Hole volume - Pin volume) x 2

Stencil
Stencil Thickness: 150 µm

PCB
PCB thickness: 1.6mm

RoHS Compliant		* NOTE: SEE PCB LAYOUT PAGE 1/3 FOR MISSING DIMENSIONS					
G				PROJECTION: 	GENERAL TOLERANCE .X = +/_ 0.2 .XX = +/_ 0.15		
F							
E							
D							
C				APPROVAL: NPr	UNIT: MM	DESCRIPTION: WR-COM - USB 3.0 SMT PLUG WITH CLIP TYPE A	SIZE A4
B					SCALE:		
A					SHEET: 3/4		
REV	DATE	FILE	BY		DRAW: AS	WERI PART NO: 692 112 030 100	

